



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2812
#5/Re-Amend A
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Application of

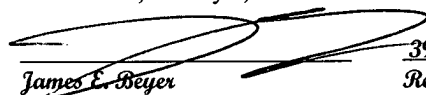
X Applicants : Salman Akram and Mike Brooks
Serial No. : 09/804,051 ✓
Filed : March 12, 2001
Title : MULTIPLE DIE PACKAGE
Docket No. : MIO 0069 PA
Confirm No. : 7513
Art Unit : 2812

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James E. Beyer
39,564
Reg. No.

Sir:

PRELIMINARY AMENDMENT

In the Specification:

Please replace the first heading and paragraph of page 1 (lines 3-7) with the following new paragraph:

A1

CROSS-REFERENCE TO RELATED APPLICATIONS

The present application is related to U.S. Patent Application Serial Nos. 09/804,421 DIE STACKING SCHEME, filed March 12, 2001 and 09/ 855,731 SEMICONDUCTOR/PRINTED CIRCUIT BOARD ASSEMBLY, AND COMPUTER SYSTEM, filed May 15, 2001.